

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ0803LS	**Issued**	08. February 2022
MA#	MA005432077		
Package	PG-TSDSON-8-36	**Weight***	35.51 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.512	1.44	1.44	14413	14413
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		103	
	non noble metal	zinc	7440-66-6	0.015	0.04		413	
	non noble metal	iron	7439-89-6	0.293	0.83		8256	
	non noble metal	copper	7440-50-8	11.903	33.52	34.40	335224	343996
wire	noble metal	gold	7440-57-5	0.028	0.08	0.08	780	780
encapsulation	organic material	carbon black	1333-86-4	0.035	0.10		982	
	plastics	epoxy resin	-	1.603	4.52		45152	
	inorganic material	silicondioxide	60676-86-0	15.789	44.47	49.09	444647	490781
leadfinish	non noble metal	tin	7440-31-5	0.420	1.18	1.18	11841	11841
plating	noble metal	silver	7440-22-4	0.003	0.01	0.01	89	89
solder	noble metal	silver	7440-22-4	0.018	0.05		500	
	non noble metal	tin	7440-31-5	0.036	0.10		1000	
	non noble metal	lead	7439-92-1	0.657	1.85	2.00	18497	19997
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			35	
	non noble metal	zinc	7440-66-6	0.005	0.01		142	
	non noble metal	iron	7439-89-6	0.101	0.28		2834	
	non noble metal	copper	7440-50-8	4.087	11.51	11.80	115092	118103
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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